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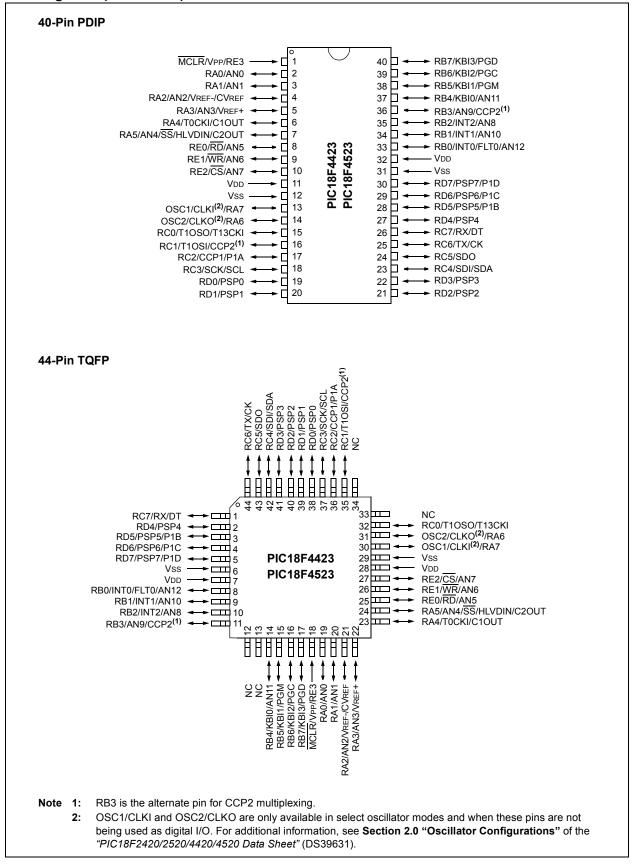
Details

| Details | |
|----------------------------|---|
| Product Status | Active |
| Core Processor | PIC |
| Core Size | 8-Bit |
| Speed | 40MHz |
| Connectivity | I ² C, SPI, UART/USART |
| Peripherals | Brown-out Detect/Reset, HLVD, POR, PWM, WDT |
| Number of I/O | 25 |
| Program Memory Size | 32KB (16K x 16) |
| Program Memory Type | FLASH |
| EEPROM Size | 256 x 8 |
| RAM Size | 1.5K x 8 |
| Voltage - Supply (Vcc/Vdd) | 4.2V ~ 5.5V |
| Data Converters | A/D 10x12b |
| Oscillator Type | Internal |
| Operating Temperature | -40°C ~ 125°C (TA) |
| Mounting Type | Surface Mount |
| Package / Case | 28-SOIC (0.295", 7.50mm Width) |
| Supplier Device Package | 28-SOIC |
| Purchase URL | https://www.e-xfl.com/product-detail/microchip-technology/pic18f2523-e-so |
| | |

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Pin Diagrams (Continued)



Pin Diagrams (Continued)

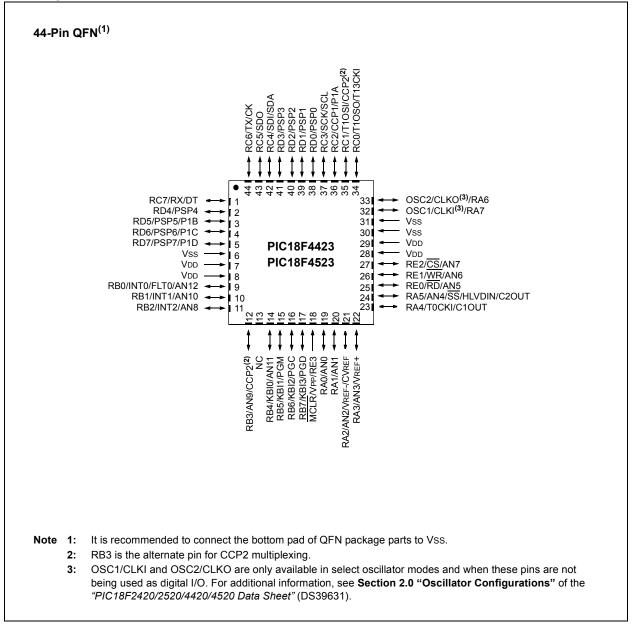


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1.0 DEVICE OVERVIEW

This document contains device-specific information for the following devices:

- PIC18F2423 PIC18LF2423
- PIC18F2523 PIC18LF2523
- PIC18F4423 PIC18LF4423
- PIC18F4523 PIC18LF4523
- Note: This data sheet documents only the devices' features and specifications that are in addition to, or different from, the features and specifications of the PIC18F2420/2520/4420/4520 devices. For information on the features and specifications shared by the PIC18F2423/2523/4423/4523 and PIC18F2420/2520/4420/4520 devices, see the "PIC18F2420/2520/4420/4520 Data Sheet" (DS39631).

This family offers the advantages of all PIC18 microcontrollers – namely, high computational performance at an economical price – with the addition of high-endurance, Enhanced Flash program memory. On top of these features, the PIC18F2423/2523/4423/4523 family introduces design enhancements that make these microcontrollers a logical choice for many high-performance, power-sensitive applications.

1.1 New Core Features

1.1.1 nanoWatt TECHNOLOGY

All of the devices in the PIC18F2423/2523/4423/4523 family incorporate a range of features that can significantly reduce power consumption during operation. Key items include:

- Alternate Run Modes: By clocking the controller from the Timer1 source or the internal oscillator block, power consumption during code execution can be reduced by as much as 90%.
- Multiple Idle Modes: The controller also can run with its CPU core disabled and the peripherals still active. In these states, power consumption can be reduced even further, to as little as 4% of normal operation requirements.
- **On-the-Fly Mode Switching:** The power-managed modes are invoked by user code during operation, allowing the user to incorporate power-saving ideas into their application's software design.
- Low Consumption in Key Modules: The power requirements for both Timer1 and the Watchdog Timer are minimized. See Section 4.0 "Electrical Characteristics" for values.

1.1.2 MULTIPLE OSCILLATOR OPTIONS AND FEATURES

All of the devices in the PIC18F2423/2523/4423/4523 family offer ten different oscillator options, allowing users a wide range of choices in developing application hardware. These include:

- Four Crystal modes, using crystals or ceramic resonators.
- Two External Clock modes, offering the option of using two pins (oscillator input and a divide-by-4 clock output) or one pin (oscillator input, with the second pin reassigned as general I/O).
- Two External RC Oscillator modes with the same pin options as the External Clock modes.
- An internal oscillator block that offers eight clock frequencies: an 8 MHz clock and an INTRC source (approximately 31 kHz), as well as a range of six user-selectable clock frequencies, between 125 kHz to 4 MHz. This option frees the two oscillator pins for use as additional general purpose I/O.
- A Phase Lock Loop (PLL) frequency multiplier, available to both the High-Speed Crystal and Internal Oscillator modes, allowing clock speeds of up to 40 MHz from the HS clock source. Used with the internal oscillator, the PLL gives users a complete selection of clock speeds, from 31 kHz to 32 MHz, all without using an external crystal or clock circuit.

Besides its availability as a clock source, the internal oscillator block provides a stable reference source that gives the family additional features for robust operation:

- Fail-Safe Clock Monitor: Constantly monitors the main clock source against a reference signal provided by the internal oscillator. If a clock failure occurs, the controller is switched to the internal oscillator block, allowing for continued operation or a safe application shutdown.
- **Two-Speed Start-up:** Allows the internal oscillator to serve as the clock source from Power-on Reset, or wake-up from Sleep mode, until the primary clock source is available.

1.2 Other Special Features

- **12-Bit A/D Converter:** This module incorporates programmable acquisition time, allowing for a channel to be selected and a conversion to be initiated without waiting for a sampling period, thereby reducing code overhead.
- **Memory Endurance:** The Enhanced Flash cells for both program memory and data EEPROM are rated to last for many thousands of erase/write cycles – up to 100,000 for program memory and 1,000,000 for EEPROM. Data retention without refresh is conservatively estimated to be greater than 40 years.
- Self-Programmability: These devices can write to their own program memory spaces under internal software control. By using a bootloader routine located in the protected Boot Block at the top of program memory, it is possible to create an application that can update itself in the field.
- Extended Instruction Set: The PIC18F2423/ 2523/4423/4523 family introduces an optional extension to the PIC18 instruction set that adds eight new instructions and an Indexed Addressing mode. This extension, enabled as a device configuration option, has been specifically designed to optimize re-entrant application code originally developed in high-level languages, such as C.
- Enhanced CCP module: In PWM mode, this module provides one, two or four modulated outputs for controlling half-bridge and full-bridge drivers. Other features include auto-shutdown, for disabling PWM outputs on interrupt or other select conditions, and auto-restart, to reactivate outputs once the condition has cleared.
- Enhanced Addressable USART: This serial communication module is capable of standard RS-232 operation and provides support for the LIN/J2602 bus protocol. Other enhancements include automatic baud rate detection and a 16-bit Baud Rate Generator for improved resolution. When the microcontroller is using the internal oscillator block, the EUSART provides stable operation for applications that talk to the outside world without using an external crystal (or its accompanying power requirement).
- Extended Watchdog Timer (WDT): This Enhanced version incorporates a 16-bit prescaler, allowing an extended time-out range that is stable across operating voltage and temperature. See Section 4.0 "Electrical Characteristics" for time-out periods.

1.3 Details on Individual Family Members

Devices in the PIC18F2423/2523/4423/4523 family are available in 28-pin and 40/44-pin packages. Block diagrams for the two groups are shown in Figure 1-1 and Figure 1-2.

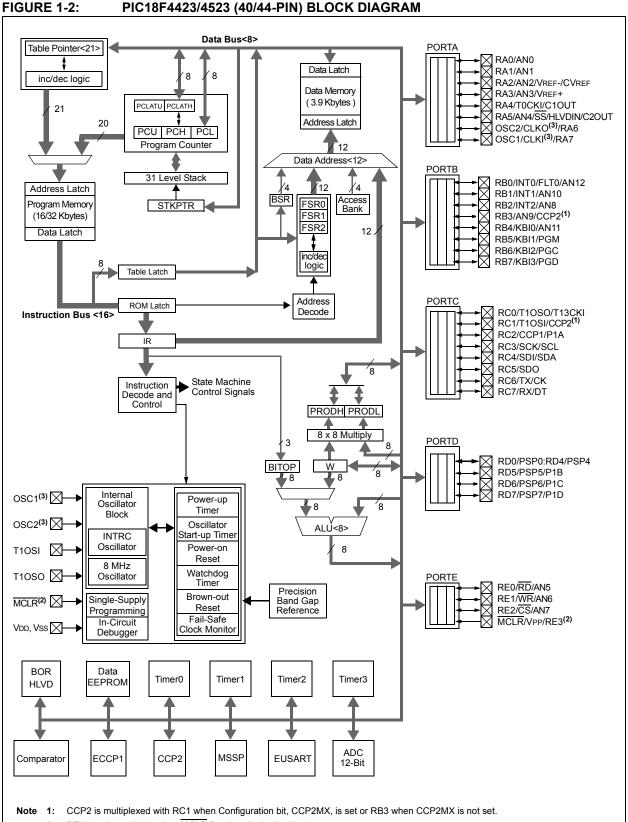
The devices are differentiated from each other in these ways:

- Flash Program Memory:
 - PIC18F2423/4423 devices 16 Kbytes
 - PIC18F2523/4523 devices 32 Kbytes
- A/D Channels:
 - PIC18F2423/2523 devices 10
 - PIC18F4423/4523 devices 13
- I/O Ports:
 - PIC18F2423/2523 devices Three bidirectional ports
 - PIC18F4423/4523 devices Five bidirectional ports
- CCP and Enhanced CCP Implementation:
 - PIC18F2423/2523 devices Two standard CCP modules
 - PIC18F4423/4523 devices One standard CCP module and one ECCP module
- Parallel Slave Port Present only on PIC18F4423/4523 devices

All other features for devices in this family are identical. These are summarized in Table 1-1.

The pinouts for all devices are listed in Table 1-2 and Table 1-3.

Members of the PIC18F2423/2523/4423/4523 family are available only as low-voltage devices, designated by "LF" (such as PIC18**LF**2423), and function over an extended VDD range of 2.0V to 5.5V.



- **2:** RE3 is only available when MCLR functionality is disabled.
- 3: OSC1/CLKI and OSC2/CLKO are only available in select oscillator modes and when these pins are not being used as digital I/O. For additional information, see Section 2.0 "Oscillator Configurations" of the "PIC18F2420/2520/4420/4520 Data Sheet" (DS39631).

| TABLE 1-2: | PIC18F2423/2523 PINOUT I/O DESCRIPTIONS |
|------------|---|
|------------|---|

| | Pin N | umber | Pin | Buffer | | | | |
|---|---------------|----------|--------|--------|---|--|--|--|
| Pin Name | PDIP, SOIC | QFN | Туре | | Description | | | |
| MCLR/VPP/RE3 | 1 | 26 | | | Master Clear (input) or programming voltage (input). | | | |
| MCLR | | | | ST | Master Clear (Reset) input. This pin is an active-low Reset to the device. | | | |
| Vpp | | | Р | | Programming voltage input. | | | |
| RE3 | | | Ι | ST | Digital input. | | | |
| OSC1/CLKI/RA7 | 9 | 6 | | | Oscillator crystal or external clock input. | | | |
| OSC1 | | | | ST | Oscillator crystal input or external clock source input. ST buffer when configured in RC mode; CMOS otherwise. | | | |
| CLKI | | | I | CMOS | External clock source input. Always associated with pin | | | |
| | | | | | function, OSC1. (See related OSC1/CLKI, OSC2/CLKO | | | |
| RA7 | | | 1/0 | TTL | pins.) General purpose I/O pin. | | | |
| OSC2/CLKO/RA6 | 10 | 7 | 1/0 | 116 | | | | |
| OSC2/CLKO/RA6 | 10 | 1 | 0 | | Oscillator crystal or clock output. Oscillator crystal output. Connects to crystal or | | | |
| 0002 | | | Ŭ | | resonator in Crystal Oscillator mode. | | | |
| CLKO | | | 0 | — | In RC mode, OSC2 pin outputs CLKO, which has 1/4 the | | | |
| RA6 | | | 1/0 | TTL | frequency of OSC1 and denotes the instruction cycle rate. General purpose I/O pin. | | | |
| | | | | 116 | | | | |
| | ompatib | • | | | CMOS = CMOS compatible input or output | | | |
| | | er input | with C | MOS le | | | | |
| O = Outpu I ² C = I ² C™ | it /SMBus | | | | P = Power | | | |

 $I^2C = I^2C^{TM}/SMBus$

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

| Pin Name | Pi | n Numb | ber Pin Buffer | | Buffer | Description | | | |
|--|------|--------|----------------|------|--|--|--|--|--|
| Pin Name | PDIP | QFN | TQFP | Туре | Туре | Description | | | |
| MCLR/VPP/RE3 MCLR | 1 | 18 | 18 | I | ST | Master Clear (input) or programming voltage (input). Master Clear (Reset) input. This pin is an active-low Reset to the device. | | | |
| VPP | | | | Р | | Programming voltage input. | | | |
| RE3 | | | | | ST | Digital input. | | | |
| OSC1/CLKI/RA7 OSC1 | 13 | 32 | 30 | I | ST | Oscillator crystal or external clock input. Oscillator crystal input or external clock source input. ST buffer when configured in RC mode; | | | |
| CLKI | | | | I | CMOS | analog otherwise. External clock source input. Always associated with pin function, OSC1. (See related OSC1/CLKI, OSC2/CLKO pins.) | | | |
| RA7 | | | | I/O | TTL | General purpose I/O pin. | | | |
| OSC2/CLKO/RA6 OSC2 | 14 | 33 | 31 | 0 | _ | Oscillator crystal or clock output. Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. | | | |
| CLKO | | | | 0 | _ | In RC mode, OSC2 pin outputs CLKO, which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate. | | | |
| RA6 | | | | I/O | TTL | General purpose I/O pin. | | | |
| Legend: TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels O = Output I^2C = $I^2C^{TM}/SMBus$ | | | | | CMOS = CMOS compatible input or output I = Input P = Power | | | | |

TABLE 1-3: PIC18F4423/4523 PINOUT I/O DESCRIPTIONS

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

| Din Nama | Pin Number | | | Pin | Buffer | Description | |
|--|------------|----------|-----------------|--------------------|-------------------------------------|--|--|
| Pin Name | PDIP | QFN | TQFP | Туре | Туре Туре | Description | |
| | | | | | | PORTA is a bidirectional I/O port. | |
| RA0/AN0 RA0 AN0 | 2 | 19 | 19 | I/O I | TTL Analog | Digital I/O. Analog Input 0. | |
| RA1/AN1 RA1 AN1 | 3 | 20 | 20 | I/O I | TTL Analog | Digital I/O. Analog Input 1. | |
| RA2/AN2/VREF-/CVREF RA2 AN2 VREF- CVREF | 4 | 21 | 21 | I/O I I O | TTL Analog Analog Analog | Digital I/O. Analog Input 2. A/D reference voltage (low) input. Comparator reference voltage output. | |
| RA3/AN3/VREF+ RA3 AN3 VREF+ | 5 | 22 | 22 | I/O I I | TTL Analog Analog | Digital I/O. Analog Input 3. A/D reference voltage (high) input. | |
| RA4/T0CKI/C1OUT RA4 T0CKI C1OUT | 6 | 23 | 23 | I/O I O | ST ST | Digital I/O. Timer0 external clock input. Comparator 1 output. | |
| RA5/AN4/SS/HLVDIN/ C2OUT RA5 AN4 SS HLVDIN C2OUT | 7 | 24 | 24 | I/O I I O | TTL Analog TTL Analog — | Digital I/O. Analog Input 4. SPI slave select input. High/Low-Voltage Detect input. Comparator 2 output. | |
| RA6 RA7 | | | | | | See the OSC2/CLKO/RA6 pin. See the OSC1/CLKI/RA7 pin. | |
| Legend: TTL = TTL ST = Schr O = Outp | mitt Trig | ger inpl | ut ut with C | CMOSI | evels | CMOS = CMOS compatible input or output I = Input P = Power | |

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

| Pin Name | Pin Number | | Pin Buffer | | Description | | |
|---|------------|-----|------------|-----------------|--|---|--|
| Fill Name | PDIP | QFN | TQFP | Туре | Туре | Description | |
| | | | | | | PORTD is a bidirectional I/O port or a Parallel Slave Port (PSP) for interfacing to a microprocessor port. These pins have TTL input buffers when the PSP module is enabled. | |
| RD0/PSP0 RD0 PSP0 | 19 | 38 | 38 | I/O I/O | ST TTL | Digital I/O. Parallel Slave Port data. | |
| RD1/PSP1 RD1 PSP1 | 20 | 39 | 39 | I/O I/O | ST TTL | Digital I/O. Parallel Slave Port data. | |
| RD2/PSP2 RD2 PSP2 | 21 | 40 | 40 | I/O I/O | ST TTL | Digital I/O. Parallel Slave Port data. | |
| RD3/PSP3 RD3 PSP3 | 22 | 41 | 41 | I/O I/O | ST TTL | Digital I/O. Parallel Slave Port data. | |
| RD4/PSP4 RD4 PSP4 | 27 | 2 | 2 | I/O I/O | ST TTL | Digital I/O. Parallel Slave Port data. | |
| RD5/PSP5/P1B RD5 PSP5 P1B | 28 | 3 | 3 | I/O I/O O | ST TTL | Digital I/O. Parallel Slave Port data. Enhanced CCP1 output. | |
| RD6/PSP6/P1C RD6 PSP6 P1C | 29 | 4 | 4 | I/O I/O O | ST TTL | Digital I/O. Parallel Slave Port data. Enhanced CCP1 output. | |
| RD7/PSP7/P1D RD7 PSP7 P1D | 30 | 5 | 5 | I/O I/O O | ST TTL | Digital I/O. Parallel Slave Port data. Enhanced CCP1 output. | |
| Legend: TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels O = Output | | | | evels | CMOS = CMOS compatible input or output I = Input P = Power | | |

TABLE 1-3: PIC18F4423/4523 PINOUT I/O DESCRIPTIONS (CONTINUED)

O = Output $I^{2}C = I^{2}C^{TM}/SMBus$

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

| REGISTER 2-2: ADCON1: A/D CONTROL REGISTER | 1 |
|--|---|
|--|---|

| U-0 | U-0 | R/W-0 | R/W-0 | R/W-0 ⁽¹⁾ | R/W ⁽¹⁾ | R/W ⁽¹⁾ | R/W ⁽¹⁾ |
|-------|-----|-------|-------|----------------------|--------------------|--------------------|--------------------|
| — | — | VCFG1 | VCFG0 | PCFG3 | PCFG2 | PCFG1 | PCFG0 |
| bit 7 | | | | | | | bit 0 |

| Legend: | | | |
|-------------------|------------------|-----------------------------|--------------------|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read | 1 as '0' |
| -n = Value at POR | '1' = Bit is set | '0' = Bit is cleared | x = Bit is unknown |

| bit 7-6 | Unimplemented: Read as '0' |
|---------|----------------------------|
|---------|----------------------------|

| bit 5 | VCFG1: Voltage Reference Configuration bit (VREF- source) |
|-------|---|
| | 1 = VREF- (AN2) |
| | 0 = Vss |
| bit 4 | VCFG0: Voltage Reference Configuration bit (VREF+ source) |
| | 1 = VREF+ (AN3) |
| | 0 = VDD |

bit 3-0 **PCFG<3:0>:** A/D Port Configuration Control bits:

| PCFG<3:0> | AN12 | AN11 | AN10 | AN9 | AN8 | AN 7 ⁽²⁾ | AN6 ⁽²⁾ | AN5 ⁽²⁾ | AN4 | AN3 | AN2 | AN1 | ANO |
|---------------------|------|------|------|-----|-----|----------------------------|--------------------|--------------------|-----|-----|-----|-----|-----|
| ₀₀₀₀ (1) | А | А | Α | Α | Α | Α | Α | Α | Α | Α | Α | Α | Α |
| 0001 | Α | А | А | Α | Α | Α | Α | Α | Α | Α | Α | Α | Α |
| 0010 | Α | А | А | Α | А | Α | Α | Α | Α | Α | Α | Α | Α |
| 0011 | D | А | А | Α | Α | Α | Α | Α | Α | А | Α | Α | Α |
| 0100 | D | D | А | Α | Α | Α | Α | Α | Α | А | Α | Α | Α |
| 0101 | D | D | D | Α | Α | Α | Α | Α | Α | Α | Α | Α | Α |
| 0110 | D | D | D | D | А | Α | Α | Α | Α | А | Α | Α | Α |
| 0111(1) | D | D | D | D | D | А | Α | Α | А | А | А | А | А |
| 1000 | D | D | D | D | D | D | Α | Α | Α | Α | Α | Α | Α |
| 1001 | D | D | D | D | D | D | D | Α | Α | Α | Α | Α | Α |
| 1010 | D | D | D | D | D | D | D | D | Α | А | Α | Α | Α |
| 1011 | D | D | D | D | D | D | D | D | D | А | Α | Α | Α |
| 1100 | D | D | D | D | D | D | D | D | D | D | Α | Α | Α |
| 1101 | D | D | D | D | D | D | D | D | D | D | D | А | Α |
| 1110 | D | D | D | D | D | D | D | D | D | D | D | D | Α |
| 1111 | D | D | D | D | D | D | D | D | D | D | D | D | D |
| A = Analog in | put | | | | D = | Digital | I/O | | | | | | |

Note 1: The POR value of the PCFG bits depends on the value of the PBADEN Configuration bit. When PBADEN = 1, PCFG<3:0> = 0000; when PBADEN = 0, PCFG<3:0> = 0111.

2: AN5 through AN7 are only available on PIC18F4423/4523 devices.

The value in the ADRESH:ADRESL registers is unknown following POR and BOR Resets and is not affected by any other Reset.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as inputs. To determine acquisition time, see **Section 2.1 "A/D Acquisition Requirements"**.

After this acquisition time has elapsed, the A/D conversion can be started. An acquisition time can be programmed to occur between setting the GO/DONE bit and the actual start of the conversion.

The following steps should be followed to perform an A/D conversion:

- 1. Configure the A/D module:
 - Configure analog pins, voltage reference and digital I/O (ADCON1)
 - Select A/D input channel (ADCON0)
 - Select A/D acquisition time (ADCON2)
 - Select A/D conversion clock (ADCON2)
 - Turn on the A/D module (ADCON0)
- 2. Configure the A/D interrupt (if desired):
 - Clear ADIF bit
 - Set ADIE bit
 - Set GIE bit
- 3. Wait the required acquisition time (if required).
- Start conversion by setting the GO/DONE bit (ADCON0<1>).

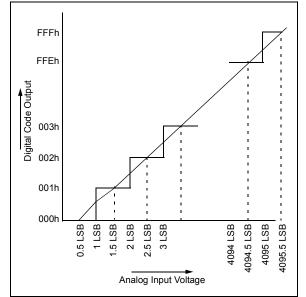
- 5. Wait for the A/D conversion to complete by either:
 - Polling for the GO/DONE bit to be cleared
 OR

· Waiting for the A/D interrupt

- 6. Read the A/D Result registers (ADRESH:ADRESL) and clear the ADIF bit, if required.
- 7. For the next conversion, go to step 1 or step 2, as required.

The A/D conversion time per bit is defined as TAD. A minimum wait of 2 TAD is required before the next acquisition starts.

FIGURE 2-2: A/D TRANSFER FUNCTION



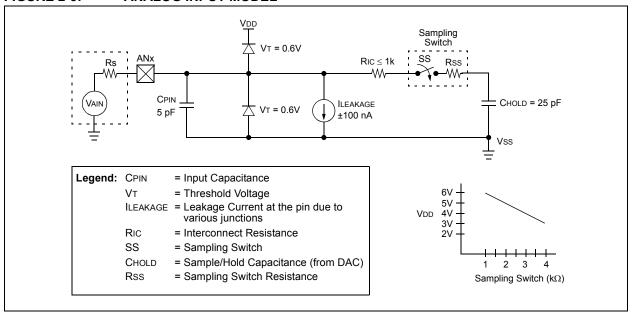


FIGURE 2-3: ANALOG INPUT MODEL

2.2 Selecting and Configuring Acquisition Time

The ADCON2 register allows the user to select an acquisition time that occurs each time the GO/DONE bit is set. It also gives users the option of having an automatically determined acquisition time.

Acquisition time may be set with the ACQT<2:0> bits (ADCON2<5:3>), which provide a range of 2 to 20 TAD. When the GO/DONE bit is set, the A/D module continues to sample the input for the selected acquisition time, then automatically begins a conversion. Since the acquisition time is programmed, there may be no need to wait for an acquisition time between selecting a channel and setting the GO/DONE bit.

Manual acquisition time is <u>selected</u> when ACQT<2:0> = 0.00. When the GO/DONE bit is set, sampling is stopped and a conversion begins. The user is responsible for ensuring the required acquisition time has passed between selecting the desired input channel and setting the GO/DONE bit. This option is also the default Reset state of the ACQT<2:0> bits and is compatible with devices that do not offer programmable acquisition times.

In either case, when the conversion is completed, the GO/DONE bit is cleared, the ADIF flag is set and the A/D begins sampling the currently selected channel again. If an acquisition time is programmed, there is nothing to indicate if the acquisition time has ended or if the conversion has begun.

2.3 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 13 TAD per 12-bit conversion. The source of the A/D conversion clock is software selectable.

There are seven possible options for TAD:

- 2 Tosc
- 32 Tosc
- 4 Tosc
- 64 ToscInternal RC Oscillator
- 8 Tosc
- 16 Tosc

For correct A/D conversions, the A/D conversion clock (TAD) must be as short as possible, but greater than the minimum TAD. (For more information, see parameter 130 on page 41.)

Table 2-2 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

| A/D Clock So | A/D Clock Source (TAD) | | |
|-------------------|------------------------|-------------------------|--|
| Operation | ADCS<2:0> | Maximum Fosc | |
| 2 Tosc | 000 | 2.50 MHz | |
| 4 Tosc | 100 | 5.00 MHz | |
| 8 Tosc | 001 | 10.00 MHz | |
| 16 Tosc | 101 | 20.00 MHz | |
| 32 Tosc | 010 | 40.00 MHz | |
| 64 Tosc | 110 | 40.00 MHz | |
| RC ⁽²⁾ | x11 | 1.00 MHz ⁽¹⁾ | |

TABLE 2-2:TAD vs. DEVICE OPERATING FREQUENCIES

Note 1: The RC source has a typical TAD time of 2.5 μ s.

2: For device frequencies above 1 MHz, the device must be in Sleep for the entire conversion or a Fosc divider should be used instead; otherwise, the A/D accuracy specification may not be met.

2.4 Operation in Power-Managed Modes

The selection of the automatic acquisition time and A/D conversion clock is determined in part by the clock source and frequency while in a power-managed mode.

If the A/D is expected to operate while the device is in a power-managed mode, the ADCS<2:0> bits in ADCON2 should be updated in accordance with the clock source to be used. The ACQT<2:0> bits do not need to be adjusted as the ADCS<2:0> bits adjust the TAD time for the new clock speed. After entering the mode, an A/D acquisition or conversion may be started. Once started, the device should continue to be clocked by the same clock source until the conversion has been completed.

If desired, the device may be placed into the corresponding Idle mode during the conversion. If the device clock frequency is less than 1 MHz, the A/D RC clock source should be selected.

Operation in Sleep mode requires the A/D FRC clock to be selected. If bits, ACQT<2:0>, are set to '000' and a conversion is started, the conversion will be delayed one instruction cycle to allow execution of the SLEEP instruction and entry to Sleep mode. The IDLEN bit (OSCCON<7>) must have already been cleared prior to starting the conversion.

2.5 Configuring Analog Port Pins

The ADCON1, TRISA, TRISB and TRISE registers all configure the A/D port pins. The port pins needed as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS<3:0> bits and the TRIS bits.

- Note 1: When reading the PORT register, all pins configured as analog input channels will read as cleared (a low level). Analog conversion on pins configured as digital pins can be performed. The voltage on the pin will be accurately converted.
 - 2: Analog levels on any pin defined as a digital input may cause the digital input buffer to consume current out of the device's specification limits.
 - **3:** The PBADEN bit in Configuration Register 3H configures PORTB pins to reset as analog or digital pins by controlling how the PCFG<3:0> bits in ADCON1 are reset.

Device ID Registers

The Device ID registers are read-only registers. They identify the device type and revision for device pro-

grammers and can be read by firmware using table

3.0 SPECIAL FEATURES OF THE CPU

Note: For additional details on the Configuration bits, refer to Section 23.1 "Configuration Bits" in the "PIC18F2420/2520/4420/4520 Data Sheet" (DS39631). Device ID information presented in this section is for the PIC18F2423/2523/4423/4523 devices only.

TABLE 3-1: DEVICE IDs

Default/ File Name Bit 7 Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 Bit 1 Bit 0 Unprogrammed Value ×××× ××××××××(2) DEVID1⁽¹⁾ 3FFFFEh DEV3 DEV2 DEV1 DEV0 REV3 REV2 REV1 REV0 XXXX XXXX(2) 3FFFFFh DEVID2⁽¹⁾ DEV11 DEV10 DEV8 DEV7 DEV6 DEV5 DEV4 DEV9

3.1

reads.

x = unknown, u = unchanged, — = unimplemented. Shaded cells are unimplemented, read as '0'. Legend:

Note 1: DEVID registers are read-only and cannot be programmed by the user.

2: See Register 3-1 and Register 3-2 for DEVID1 and DEVID2 values.

REGISTER 3-1: DEVID1: DEVICE ID REGISTER 1 FOR PIC18F2423/2523/4423/4523

| R | R | R | R | R | R | R | R |
|-------|------|------|------|------|------|------|-------|
| DEV3 | DEV2 | DEV1 | DEV0 | REV3 | REV2 | REV1 | REV0 |
| bit 7 | | | | | | | bit 0 |

| Legend: | | | |
|--------------------------|----------------------|-------------------------------------|--|
| R = Read-only bit | P = Programmable bit | U = Unimplemented bit, read as '0' | |
| -n = Value when device i | s unprogrammed | u = Unchanged from programmed state | |

| bit 7-4 | DEV<3:0>: Device ID bits |
|---------|--|
| | 1101 = PIC18F4423 |
| | 1001 = PIC18F4523 |
| | 0101 = PIC18F2423 |
| | 0001 = PIC18F2523 |
| bit 3-0 | REV<3:0>: Revision ID bits |
| | These bits are used to indicate the device revision. |

PIC18F2423/2523/4423/4523

REGISTER 3-2: DEVID2: DEVICE ID REGISTER 2 FOR PIC18F2423/2523/4423/4523

| R | R | R | R | R | R | R | R | |
|--|----------------------|---------------------|---------------------|------------------------------------|---------------------|---------------------|---------------------|--|
| DEV11 ⁽¹⁾ | DEV10 ⁽¹⁾ | DEV9 ⁽¹⁾ | DEV8 ⁽¹⁾ | DEV7 ⁽¹⁾ | DEV6 ⁽¹⁾ | DEV5 ⁽¹⁾ | DEV4 ⁽¹⁾ | |
| bit 7 | | | | | | • | bit 0 | |
| | | | | | | | | |
| Legend: | | | | | | | | |
| R = Read-only I | bit | P = Programr | nable bit | U = Unimplemented bit, read as '0' | | | | |
| -n = Value when device is unprogrammed | | | u = Unchange | ed from progran | nmed state | | | |

bit 7-0 **DEV<11:4>:** Device ID bits⁽¹⁾ These bits are used with the DEV<3:0> bits in Device ID Register 1 to identify the part number. 0001 0001 = PIC18F2423/2523 devices 0001 0000 = PIC18F4423/4523 devices

Note 1: These values for DEV<11:4> may be shared with other devices. The specific device is always identified by using the entire DEV<11:0> bit sequence.

APPENDIX A: REVISION HISTORY

Revision A (June 2006)

Original data sheet for PIC18F2423/2523/4423/4523 devices.

Revision B (January 2007)

This revision includes updates to the packaging diagrams.

Revision C (September 2009)

Electrical specifications updated. Preliminary condition status removed. Converted document to the "mini data sheet" format.

APPENDIX B: DEVICE DIFFERENCES

The differences between the devices listed in this data sheet are shown in Table B-1.

| Features | PIC18F2423 | PIC18F2523 | PIC18F4423 | PIC18F4523 |
|---|--|--|--|--|
| Program Memory (Bytes) | 16384 | 32768 | 16384 | 32768 |
| Program Memory (Instructions) | 8192 | 16384 | 8192 | 16384 |
| Interrupt Sources | 19 | 19 | 20 | 20 |
| I/O Ports | Ports A, B, C, (E) | Ports A, B, C, (E) | Ports A, B, C, D, E | Ports A, B, C, D, E |
| Capture/Compare/PWM Modules | 2 | 2 | 1 | 1 |
| Enhanced Capture/Compare/PWM Modules | 0 | 0 | 1 | 1 |
| Parallel Communications (PSP) | No | No | Yes | Yes |
| 12-Bit Analog-to-Digital Module | 10 Input Channels | 10 Input Channels | 13 Input Channels | 13 Input Channels |
| Packages | 28-Pin PDIP 28-Pin SOIC 28-Pin QFN | 28-Pin PDIP 28-Pin SOIC 28-Pin QFN | 40-Pin PDIP 44-Pin TQFP 44-Pin QFN | 40-Pin PDIP 44-Pin TQFP 44-Pin QFN |

TABLE B-1:DEVICE DIFFERENCES

APPENDIX C: CONVERSION CONSIDERATIONS

This appendix discusses the considerations for converting from previous versions of a device to the ones listed in this data sheet. Typically, these changes are due to the differences in the process technology used. An example of this type of conversion is from a PIC16C74A to a PIC16C74B.

Not Applicable

APPENDIX D: MIGRATION FROM BASELINE TO ENHANCED DEVICES

This section discusses how to migrate from a Baseline device (i.e., PIC16C5X) to an Enhanced MCU device (i.e., PIC18FXXX).

The following are the list of modifications over the PIC16C5X microcontroller family:

Not Currently Available

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